

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP6961	REV: E	SVN REV:	Not In VersionControl
IGNORE -> Top Overlay				
PLOT NAME = Top Assembly Drawing	GENERATED : 1/22/2	2014 10:55:02	AM	TEXAS INSTRUMENTS

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP6961	REV: E	SVN REV:	: Not In VersionControl
	Bottom Overlay <- JAONDI			
PLOT NAME = Bottom Assembly Drawing	GENERATED : 1/22/2	2014 10:55:03	AM	TEXAS INSTRUMENTS

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